



5850HR

Heavy Ribbon Wedge Bonder

Bond System

Wire types	Aluminium-Ribbon up to 2000 x 300 µm Copper wire 300 ... 500 µm on 4" spool Ribbons in Cu or composite materials motorized wire despooler (optional)
Bond head	Wedge-Wedge for heavy ribbon Standard wedges of 2" length, self-adjusting clip-on wire guide and quick-change cutter blade Programmable Voice-coil bond force system 0 up to 1800 cN with mechanically increased bondforce max. 6000 cN
Ultrasonic System	F&K Generator 60 kHz (optionally 40, 90, 120 kHz)

Bonder Base

Axes	Working area X/Y-axis 200 x 150 mm; step resolution 0,3 µm Programmable Z axis with 100 mm stroke; step resolution 0,3 µm
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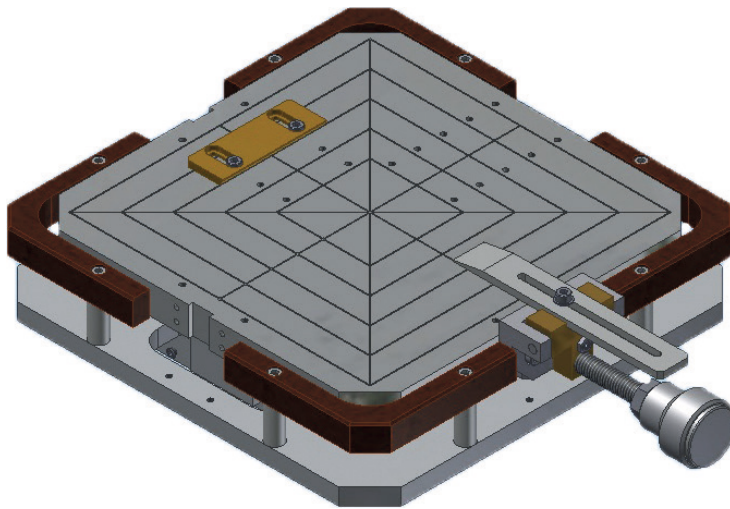
The Heavy-Wire version of the automatic wire bonders in our Series 58 featuring exchangeable bond heads.

A fully automatic mode makes it ideally suited for medium-scale production. Parts to be bonded are fed manually by the operator, but the bonds are produced completely without operator influence. Thanks to the built-in pattern recognition.

Single bonds can be made within seconds, making the machine perfect for R&D, Pilot manufacturing and middle volume production

BONDING THE STARS

Hardware	Dual-Core PC with Windows 7 OS, Ethernet, USB 2.0/3.0 LCD Colour Display 22" GigE-CCD-Colour Camera, 5 Mpixel Fully networkable in TCP/IP servers for program archiving
Software	From single bonds up to complex programmes, teach-in programming, also in step-and-repeat Loop shapes can be stored in libraries Optionally: pattern recognition with pseudo-error check
Dimensions	W x D x H 92 x 71 x 65 cm, weight approx. 80 kg
Connections	100...240 VAC, single phase, 50/60 Hz, max. 230 VA Ø 6 mm standard vacuum tubing
Workholder	



Standard-Substrataufnahme
für Bauteile bis 6" x 6"
mit Vakuum und mechanischer Klemmung

optional:



4x4" Substrataufnahme mit
gummierter Oberfläche;
mechanischer Klemmung

